

ABSTRACT

A heat-dissipating plate module installed on a heat-generating component of an electronic device for dissipating heat generated there by is disclosed. The heat-dissipating plate module is comprised of a heat-conductive base and several heat-dissipating plates.

- 5 The heat-conductive base is in direct contact with the heat-generating component for heat transfer. Each heat-dissipating plate has several pillar-like protruding parts for increasing the dissipation area. The protruding parts of adjacent heat-dissipating plates are distributed in a non-overlapping way so that the airflow paths in between are continuously curved. This can elongate the heat transfer time to enhance the heat dissipation efficiency.